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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I ² C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	24
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.85V ~ 3.8V
Data Converters	A/D 24x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32pg1b100f256gm32-c0

1. Feature List

The EFM32PG1 highlighted features are listed below.

- **ARM Cortex-M4 CPU platform**
 - High performance 32-bit processor @ up to 40 MHz
 - DSP instruction support and Floating Point Unit
 - Memory Protection Unit
 - Wake-up Interrupt Controller
- **Flexible Energy Management System**
 - 63 μ A/MHz in Energy Mode 0 (EM0)
 - 2.5 μ A EM2 DeepSleep current (RTCC running with state and RAM retention)
 - 0.58 μ A EM4H Hibernate Mode (128 byte RAM retention)
- **Up to 256 kB flash program memory**
- **32 kB RAM data memory**
- **Up to 32 General Purpose I/O Pins**
 - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
 - Configurable peripheral I/O locations
 - Asynchronous external interrupts
 - Output state retention and wake-up from Shutoff Mode
- **Hardware Cryptography**
 - AES 128/256-bit keys
 - ECC B/K163, B/K233, P192, P224, P256
 - SHA-1 and SHA-2 (SHA-224 and SHA-256)
- **Timers/Counters**
 - 2 \times 16-bit Timer/Counter
 - 3 + 4 Compare/Capture/PWM channels
 - 1 \times 32-bit Real Time Counter and Calendar
 - 1 \times 32-bit Ultra Low Energy CRYOTIMER for periodic wake-up from any Energy Mode
 - 16-bit Low Energy Timer for waveform generation
 - 16-bit Pulse Counter with asynchronous operation
 - Watchdog Timer with dedicated RC oscillator
- **8 Channel DMA Controller**
- **12 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling**
- **Communication Interfaces**
 - 2 \times Universal Synchronous/Asynchronous Receiver/ Transmitter
 - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S/LIN
 - Triple buffered full/half-duplex operation with flow control
 - Low Energy UART
 - Autonomous operation with DMA in Deep Sleep Mode
 - I²C Interface with SMBus support
 - Address recognition in EM3 Stop Mode
- **Ultra Low-Power Precision Analog Peripherals**
 - 12-bit 1 Msamples/s Analog to Digital Converter
 - 2 \times Analog Comparator
 - Digital to Analog Current Converter
 - Up to 32 pins connected to analog channels (APORT) shared between Analog Comparators, ADC, and IDAC
- **Ultra efficient Power-on Reset and Brown-Out Detector**
- **Debug Interface**
 - 2-pin Serial Wire Debug interface
 - 1-pin Serial Wire Viewer
 - JTAG (programming only)
- **Wide Operating Range**
 - 1.85 V to 3.8 V single power supply
 - Integrated dc-dc, down to 1.8 V output with up to 200 mA load current for system
 - Standard (-40 °C to 85 °C T_{AMB}) and Extended (-40 °C to 125 °C T_J) temperature grades available
- **Packages**
 - 7 mm \times 7 mm QFN48
 - 5 mm \times 5 mm QFN32
- **Pre-Programmed UART Bootloader**
- **Full Software Support**
 - CMSIS register definitions
 - Low-power Hardware Abstraction Layer (HAL)
 - Portable software components
 - Third-party middleware
 - Free and available example code

2. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	DC-DC Converter	GPIO	Package	Temp Range
EFM32PG1B200F256GM48-C0	256	32	Yes	32	QFN48	-40 to +85
EFM32PG1B200F256IM48-C0	256	32	Yes	32	QFN48	-40 to +125
EFM32PG1B200F128GM48-C0	128	32	Yes	32	QFN48	-40 to +85
EFM32PG1B200F256GM32-C0	256	32	Yes	20	QFN32	-40 to +85
EFM32PG1B200F256IM32-C0	256	32	Yes	20	QFN32	-40 to +125
EFM32PG1B200F128GM32-C0	128	32	Yes	20	QFN32	-40 to +85
EFM32PG1B100F256GM32-C0	256	32	No	24	QFN32	-40 to +85
EFM32PG1B100F256IM32-C0	256	32	No	24	QFN32	-40 to +125
EFM32PG1B100F128GM32-C0	128	32	No	24	QFN32	-40 to +85

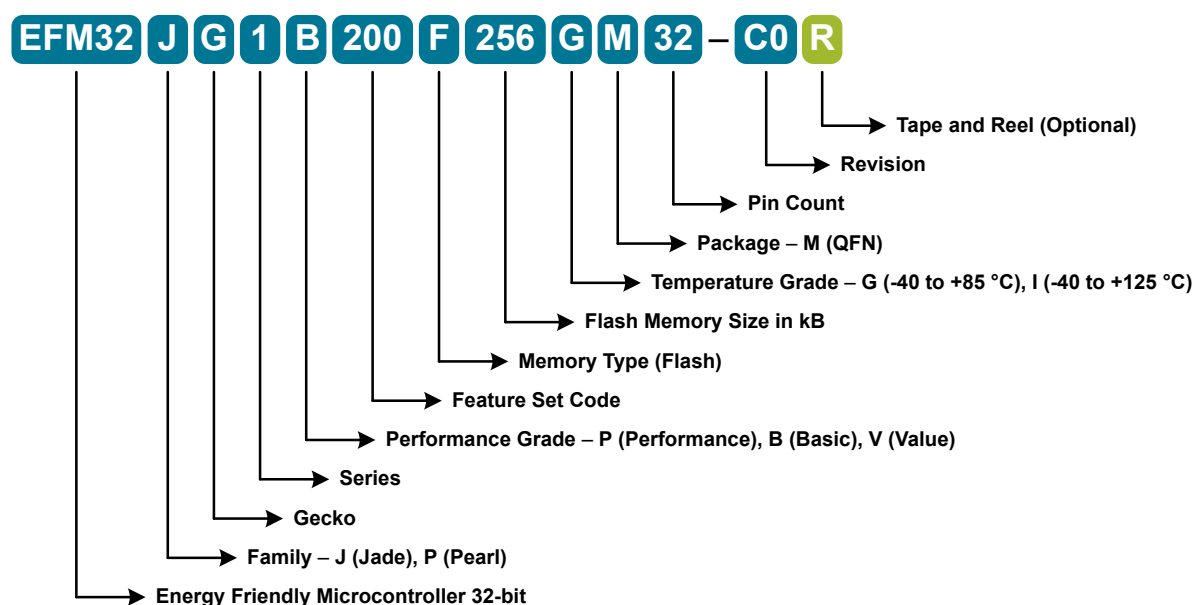


Figure 2.1. OPN Decoder

3.6.3 Inter-Integrated Circuit Interface (I²C)

The I²C module provides an interface between the MCU and a serial I²C bus. It is capable of acting as both a master and a slave and supports multi-master buses. Standard-mode, fast-mode and fast-mode plus speeds are supported, allowing transmission rates from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also available, allowing implementation of an SMBus-compliant system. The interface provided to software by the I²C module allows precise timing control of the transmission process and highly automated transfers. Automatic recognition of slave addresses is provided in active and low energy modes.

3.6.4 Peripheral Reflex System (PRS)

The Peripheral Reflex System provides a communication network between different peripheral modules without software involvement. Peripheral modules producing Reflex signals are called producers. The PRS routes Reflex signals from producers to consumer peripherals which in turn perform actions in response. Edge triggers and other functionality can be applied by the PRS. The PRS allows peripheral to act autonomously without waking the MCU core, saving power.

3.7 Security Features

3.7.1 GPCRC (General Purpose Cyclic Redundancy Check)

The GPCRC module implements a Cyclic Redundancy Check (CRC) function. It supports both 32-bit and 16-bit polynomials. The supported 32-bit polynomial is 0x04C11DB7 (IEEE 802.3), while the 16-bit polynomial can be programmed to any value, depending on the needs of the application.

3.7.2 Crypto Accelerator (CRYPTO)

The Crypto Accelerator is a fast and energy-efficient autonomous hardware encryption and decryption accelerator. EFM32PG1 devices support AES encryption and decryption with 128- or 256-bit keys, ECC over both GF(P) and GF(2^m), and SHA-1 and SHA-2 (SHA-224 and SHA-256).

Supported block cipher modes of operation for AES include: ECB, CTR, CBC, PCBC, CFB, OFB, GCM, CBC-MAC, GMAC and CCM.

Supported ECC NIST recommended curves include P-192, P-224, P-256, K-163, K-233, B-163 and B-233.

The CRYPTO module allows fast processing of GCM (AES), ECC and SHA with little CPU intervention. CRYPTO also provides trigger signals for DMA read and write operations.

3.8 Analog

3.8.1 Analog Port (APORT)

The Analog Port (APORT) is an analog interconnect matrix allowing access to many analog modules on a flexible selection of pins. Each APORT bus consists of analog switches connected to a common wire. Since many clients can operate differentially, buses are grouped by X/Y pairs.

3.8.2 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs are selected from among internal references and external pins. The tradeoff between response time and current consumption is configurable by software. Two 6-bit reference dividers allow for a wide range of internally-programmable reference sources. The ACMP can also be used to monitor the supply voltage. An interrupt can be generated when the supply falls below or rises above the programmable threshold.

3.8.3 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to 1 Msps. The output sample resolution is configurable and additional resolution is possible using integrated hardware for averaging over multiple samples. The ADC includes integrated voltage references and an integrated temperature sensor. Inputs are selectable from a wide range of sources, including pins configurable as either single-ended or differential.

3.11 Memory Map

The EFM32PG1 memory map is shown in the figures below. RAM and flash sizes are for the largest memory configuration.

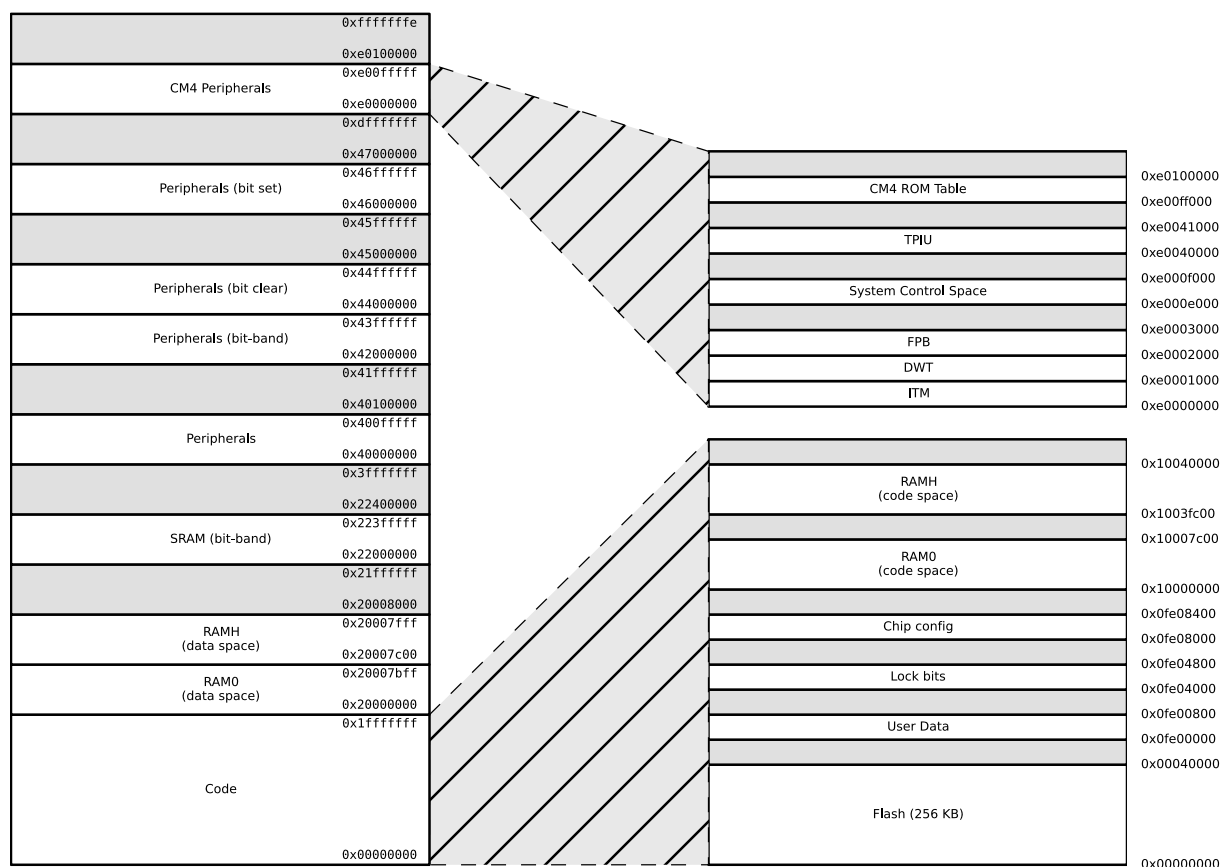


Figure 3.2. EFM32PG1 Memory Map — Core Peripherals and Code Space

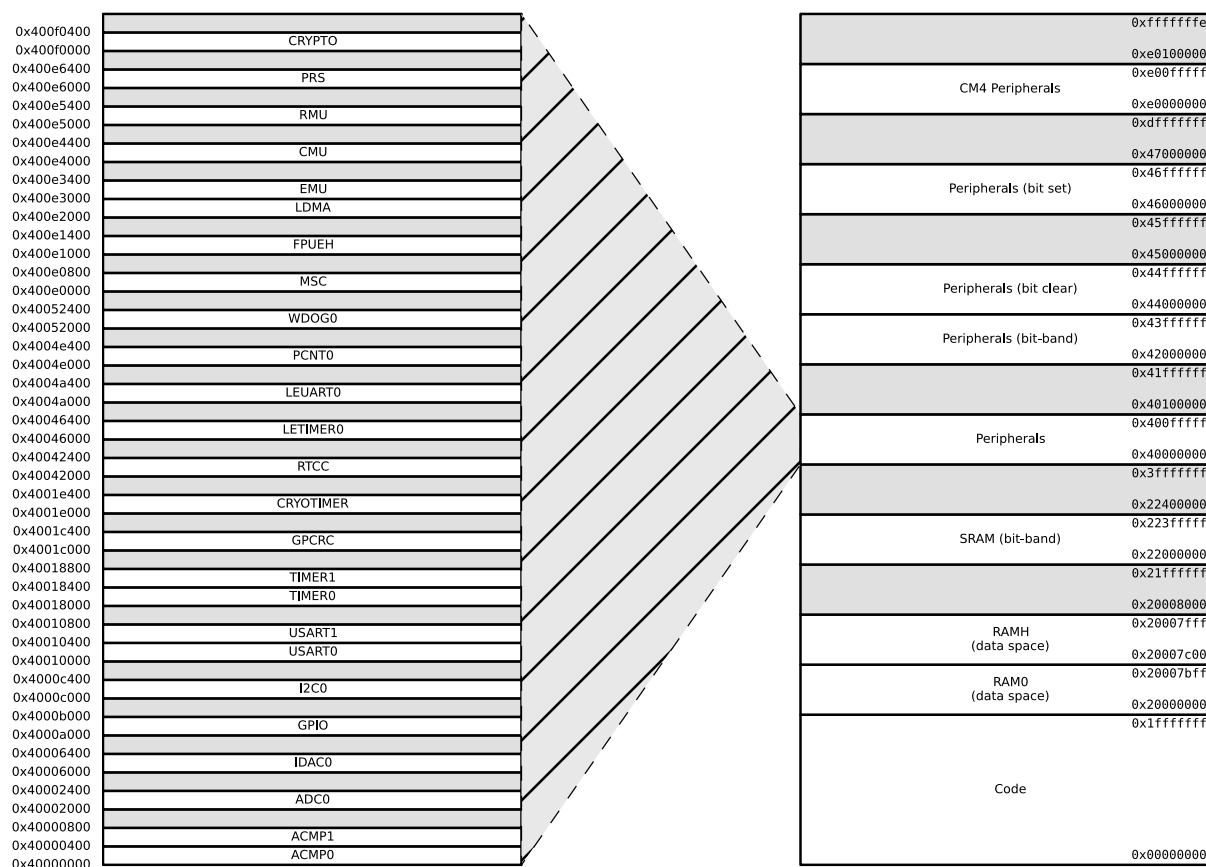


Figure 3.3. EFM32PG1 Memory Map — Peripherals

3.12 Configuration Summary

The features of the EFM32PG1 are a subset of the feature set described in the device reference manual. The table below describes device specific implementation of the features. Remaining modules support full configuration.

Table 3.1. Configuration Summary

Module	Configuration	Pin Connections
USART0	IrDA SmartCard	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	IrDA I ² S SmartCard	US1_TX, US1_RX, US1_CLK, US1_CS
TIMER0	with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1		TIM1_CC[3:0]

4.1.2 Operating Conditions

When assigning supply sources, the following requirements must be observed:

- VREGVDD must be the highest voltage in the system
- VREGVDD = AVDD
- DVDD ≤ AVDD
- IOVDD ≤ AVDD

4.1.2.1 General Operating Conditions

Table 4.2. General Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating temperature range	T _{OP}	-G temperature grade, Ambient Temperature	-40	25	85	°C
		-I temperature grade, Junction Temperature	-40	25	125	°C
AVDD Supply voltage ¹	V _{AVDD}		1.85	3.3	3.8	V
VREGVDD Operating supply voltage ^{1 2}	V _{VREGVDD}	DCDC in regulation	2.4	3.3	3.8	V
		DCDC in bypass, 50mA load	1.85	3.3	3.8	V
		DCDC not in use. DVDD externally shorted to VREGVDD	1.85	3.3	3.8	V
VREGVDD Current	I _{VREGVDD}	DCDC in bypass, T _{amb} ≤ 85 °C	—	—	200	mA
		DCDC in bypass, T _{amb} > 85 °C	—	—	100	mA
DVDD Operating supply voltage	V _{DVDD}		1.62	—	V _{VREGVDD}	V
IOVDD Operating supply voltage	V _{IOVDD}		1.62	—	V _{VREGVDD}	V
Difference between AVDD and VREGVDD, ABS(AVDD-VREGVDD)	dV _{DD}		—	—	0.1	V
HFCLK frequency	f _{CORE}	0 wait-states (MODE = WS0) ³	—	—	26	MHz
		1 wait-states (MODE = WS1) ³	—	—	40	MHz

Note:

1. VREGVDD must be tied to AVDD. Both VREGVDD and AVDD minimum voltages must be satisfied for the part to operate.
2. The minimum voltage required in bypass mode is calculated using R_{BYP} from the DCDC specification table. Requirements for other loads can be calculated as V_{DVDD_min} + I_{LOAD} * R_{BYP_max}
3. In MSC_READCTRL register

4.1.6 Wake up times

Table 4.8. Wake up times

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Wake up from EM2 Deep Sleep	t _{EM2_WU}	Code execution from flash	—	10.7	—	μs
		Code execution from RAM	—	3	—	μs
Wakeup time from EM1 Sleep	t _{EM1_WU}	Executing from flash	—	3	—	AHB Clocks
		Executing from RAM	—	3	—	AHB Clocks
Wake up from EM3 Stop	t _{EM3_WU}	Executing from flash	—	10.7	—	μs
		Executing from RAM	—	3	—	μs
Wake up from EM4H Hiber-nate ¹	t _{EM4H_WU}	Executing from flash	—	60	—	μs
Wake up from EM4S Shut-off ¹	t _{EM4S_WU}		—	290	—	μs
Note: 1. Time from wakeup request until first instruction is executed. Wakeup results in device reset.						

4.1.7 Brown Out Detector

Table 4.9. Brown Out Detector

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DVDD BOD threshold	$V_{DVDDBOD}$	DVDD rising	—	—	1.62	V
		DVDD falling	1.35	—	—	V
DVDD BOD hysteresis	$V_{DVDDBOD_HYST}$		—	24	—	mV
DVDD response time	$t_{DVDDBOD_DELAY}$	Supply drops at 0.1V/ μs rate	—	2.4	—	μs
AVDD BOD threshold	$V_{AVDDBOD}$	AVDD rising	—	—	1.85	V
		AVDD falling	1.62	—	—	V
AVDD BOD hysteresis	$V_{AVDDBOD_HYST}$		—	21	—	mV
AVDD response time	$t_{AVDDBOD_DELAY}$	Supply drops at 0.1V/ μs rate	—	2.4	—	μs
EM4 BOD threshold	V_{EM4BOD}	AVDD rising	—	—	1.7	V
		AVDD falling	1.45	—	—	V
EM4 BOD hysteresis	V_{EM4BOD_HYST}		—	46	—	mV
EM4 response time	t_{EM4BOD_DELAY}	Supply drops at 0.1V/ μs rate	—	300	—	μs

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Comparator delay ⁴	$t_{ACMPDELAY}$	BIASPROG ² = 1, FULLBIAS ² = 0	—	30	—	μs
		BIASPROG ² = 0x10, FULLBIAS ² = 0	—	3.7	—	μs
		BIASPROG ² = 0x20, FULLBIAS ² = 1	—	35	—	ns
Offset voltage	$V_{ACMPOFFSET}$	BIASPROG ² = 0x10, FULLBIAS ² = 1	-35	—	35	mV
Reference Voltage	$V_{ACMPREF}$	Internal 1.25 V reference	1	1.25	1.47	V
		Internal 2.5 V reference	2	2.5	2.8	V
Capacitive Sense Internal Resistance	R_{CSRES}	CSRESSEL ⁵ = 0	—	inf	—	k Ω
		CSRESSEL ⁵ = 1	—	15	—	k Ω
		CSRESSEL ⁵ = 2	—	27	—	k Ω
		CSRESSEL ⁵ = 3	—	39	—	k Ω
		CSRESSEL ⁵ = 4	—	51	—	k Ω
		CSRESSEL ⁵ = 5	—	102	—	k Ω
		CSRESSEL ⁵ = 6	—	164	—	k Ω
		CSRESSEL ⁵ = 7	—	239	—	k Ω

Note:

1. ACMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD
2. In ACMPn_CTRL register
3. In ACMPn_HYSTERESIS register
4. ± 100 mV differential drive
5. In ACMPn_INPUTSEL register

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given as:

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$$

$I_{ACMPREF}$ is zero if an external voltage reference is used.

4.1.15 I2C

I2C Standard-mode (Sm)

Table 4.21. I2C Standard-mode (Sm)¹

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency ²	f_{SCL}		0	—	100	kHz
SCL clock low time	t_{LOW}		4.7	—	—	μs
SCL clock high time	t_{HIGH}		4	—	—	μs
SDA set-up time	$t_{\text{SU,DAT}}$		250	—	—	ns
SDA hold time ³	$t_{\text{HD,DAT}}$		100	—	3450	ns
Repeated START condition set-up time	$t_{\text{SU,STA}}$		4.7	—	—	μs
(Repeated) START condition hold time	$t_{\text{HD,STA}}$		4	—	—	μs
STOP condition set-up time	$t_{\text{SU,STO}}$		4	—	—	μs
Bus free time between a STOP and START condition	t_{BUF}		4.7	—	—	μs

Note:

1. For CLHR set to 0 in the I2Cn_CTRL register
2. For the minimum HPERCLK frequency required in Standard-mode, refer to the I2C chapter in the reference manual
3. The maximum SDA hold time ($t_{\text{HD,DAT}}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW})

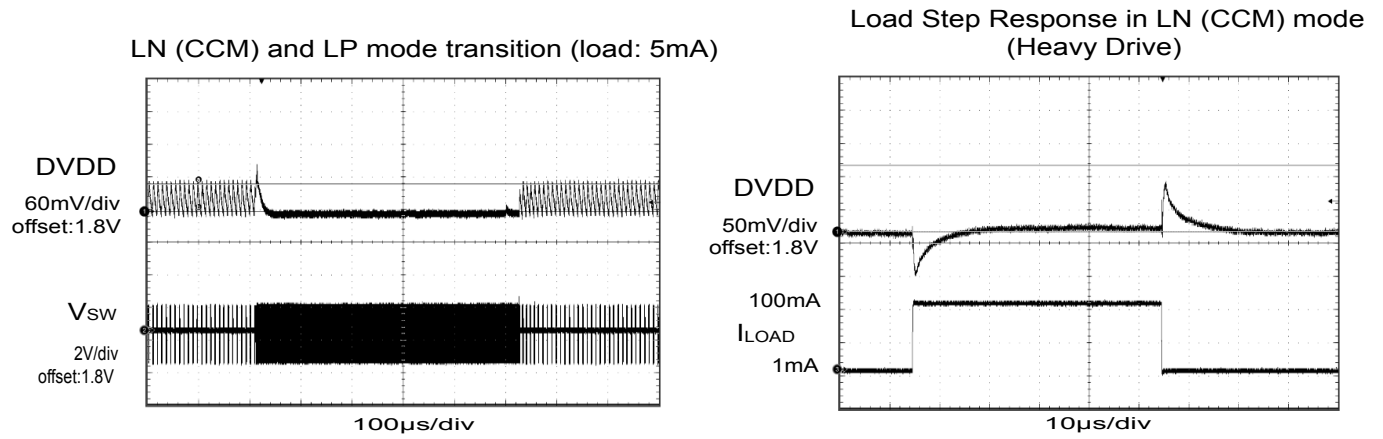


Figure 4.7. DC-DC Converter Transition Waveforms

5. Typical Connection Diagrams

5.1 Power

Typical power supply connections for direct supply, without using the internal dc-dc converter, are shown in [Figure 5.1 EFM32PG1 Typical Application Circuit, Direct Supply, No DC-DC Converter on page 47](#).

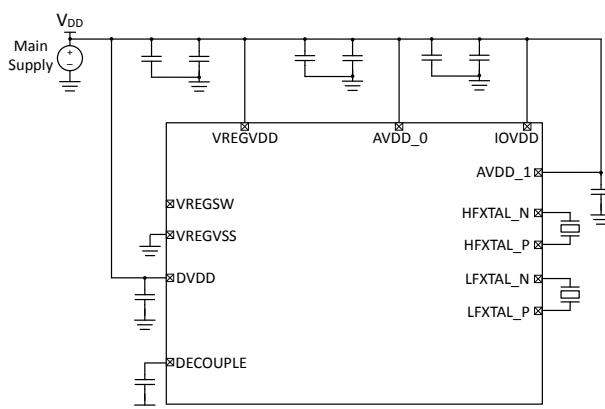


Figure 5.1. EFM32PG1 Typical Application Circuit, Direct Supply, No DC-DC Converter

A typical application circuit using the internal dc-dc converter is shown in [Figure 5.2 EFM32PG1 Typical Application Circuit Using the DC-DC Converter on page 47](#). The MCU operates from the dc-dc converter supply.

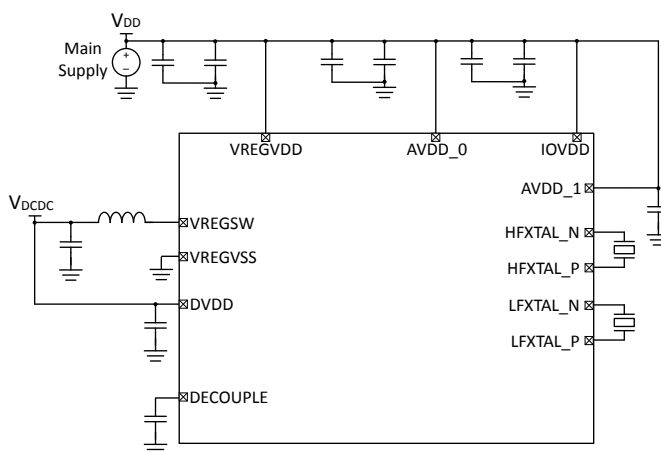


Figure 5.2. EFM32PG1 Typical Application Circuit Using the DC-DC Converter

5.2 Other Connections

Other components or connections may be required to meet the system-level requirements. Application Note AN0002: "Hardware Design Considerations" contains detailed information on these connections. Application Notes can be accessed on the Silicon Labs website (www.silabs.com/32bit-appnotes).

Table 6.1. QFN48 with DC-DC Device Pinout

QFN48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	RFVSS	Radio Ground			
1	PF0	BUSAX BUSBY	TIM0_CC0 #24 TIM0_CC1 #23 TIM0_CC2 #22 TIM0_CDTI0 #21 TIM0_CDTI1 #20 TIM0_CDTI2 #19 TIM1_CC0 #24 TIM1_CC1 #23 TIM1_CC2 #22 TIM1_CC3 #21 LE- TIM0_OUT0 #24 LE- TIM0_OUT1 #23 PCNT0_S0IN #24 PCNT0_S1IN #23	US0_TX #24 US0_RX #23 US0_CLK #22 US0_CS #21 US0_CTS #20 US0_RTS #19 US1_TX #24 US1_RX #23 US1_CLK #22 US1_CS #21 US1_CTS #20 US1_RTS #19 LEU0_TX #24 LEU0_RX #23 I2C0_SDA #24 I2C0_SCL #23	PRS_CH0 #0 PRS_CH1 #7 PRS_CH2 #6 PRS_CH3 #5 ACMP0_O #24 ACMP1_O #24 DBG_SWCLKTCK #0 BOOT_TX
2	PF1	BUSAY BUSBX	TIM0_CC0 #25 TIM0_CC1 #24 TIM0_CC2 #23 TIM0_CDTI0 #22 TIM0_CDTI1 #21 TIM0_CDTI2 #20 TIM1_CC0 #25 TIM1_CC1 #24 TIM1_CC2 #23 TIM1_CC3 #22 LE- TIM0_OUT0 #25 LE- TIM0_OUT1 #24 PCNT0_S0IN #25 PCNT0_S1IN #24	US0_TX #25 US0_RX #24 US0_CLK #23 US0_CS #22 US0_CTS #21 US0_RTS #20 US1_TX #25 US1_RX #24 US1_CLK #23 US1_CS #22 US1_CTS #21 US1_RTS #20 LEU0_TX #25 LEU0_RX #24 I2C0_SDA #25 I2C0_SCL #24	PRS_CH0 #1 PRS_CH1 #0 PRS_CH2 #7 PRS_CH3 #6 ACMP0_O #25 ACMP1_O #25 DBG_SWDIOTMS #0 BOOT_RX
3	PF2	BUSAX BUSBY	TIM0_CC0 #26 TIM0_CC1 #25 TIM0_CC2 #24 TIM0_CDTI0 #23 TIM0_CDTI1 #22 TIM0_CDTI2 #21 TIM1_CC0 #26 TIM1_CC1 #25 TIM1_CC2 #24 TIM1_CC3 #23 LE- TIM0_OUT0 #26 LE- TIM0_OUT1 #25 PCNT0_S0IN #26 PCNT0_S1IN #25	US0_TX #26 US0_RX #25 US0_CLK #24 US0_CS #23 US0_CTS #22 US0_RTS #21 US1_TX #26 US1_RX #25 US1_CLK #24 US1_CS #23 US1_CTS #22 US1_RTS #21 LEU0_TX #26 LEU0_RX #25 I2C0_SDA #26 I2C0_SCL #25	CMU_CLK0 #6 PRS_CH0 #2 PRS_CH1 #1 PRS_CH2 #0 PRS_CH3 #7 ACMP0_O #26 ACMP1_O #26 DBG_TDO #0 DBG_SWO #0 GPIO_EM4WU0

QFN48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
20	PD11	BUSCY BUSDX	TIM0_CC0 #19 TIM0_CC1 #18 TIM0_CC2 #17 TIM0_CDTI0 #16 TIM0_CDTI1 #15 TIM0_CDTI2 #14 TIM1_CC0 #19 TIM1_CC1 #18 TIM1_CC2 #17 TIM1_CC3 #16 LE- TIM0_OUT0 #19 LE- TIM0_OUT1 #18 PCNT0_S0IN #19 PCNT0_S1IN #18	US0_TX #19 US0_RX #18 US0_CLK #17 US0_CS #16 US0_CTS #15 US0_RTS #14 US1_TX #19 US1_RX #18 US1_CLK #17 US1_CS #16 US1_CTS #15 US1_RTS #14 LEU0_TX #19 LEU0_RX #18 I2C0_SDA #19 I2C0_SCL #18	PRS_CH3 #10 PRS_CH4 #2 PRS_CH5 #1 PRS_CH6 #13 ACMP0_O #19 ACMP1_O #19
21	PD12	BUSCX BUSDY	TIM0_CC0 #20 TIM0_CC1 #19 TIM0_CC2 #18 TIM0_CDTI0 #17 TIM0_CDTI1 #16 TIM0_CDTI2 #15 TIM1_CC0 #20 TIM1_CC1 #19 TIM1_CC2 #18 TIM1_CC3 #17 LE- TIM0_OUT0 #20 LE- TIM0_OUT1 #19 PCNT0_S0IN #20 PCNT0_S1IN #19	US0_TX #20 US0_RX #19 US0_CLK #18 US0_CS #17 US0_CTS #16 US0_RTS #15 US1_TX #20 US1_RX #19 US1_CLK #18 US1_CS #17 US1_CTS #16 US1_RTS #15 LEU0_TX #20 LEU0_RX #19 I2C0_SDA #20 I2C0_SCL #19	PRS_CH3 #11 PRS_CH4 #3 PRS_CH5 #2 PRS_CH6 #14 ACMP0_O #20 ACMP1_O #20
22	PD13	BUSCY BUSDX	TIM0_CC0 #21 TIM0_CC1 #20 TIM0_CC2 #19 TIM0_CDTI0 #18 TIM0_CDTI1 #17 TIM0_CDTI2 #16 TIM1_CC0 #21 TIM1_CC1 #20 TIM1_CC2 #19 TIM1_CC3 #18 LE- TIM0_OUT0 #21 LE- TIM0_OUT1 #20 PCNT0_S0IN #21 PCNT0_S1IN #20	US0_TX #21 US0_RX #20 US0_CLK #19 US0_CS #18 US0_CTS #17 US0_RTS #16 US1_TX #21 US1_RX #20 US1_CLK #19 US1_CS #18 US1_CTS #17 US1_RTS #16 LEU0_TX #21 LEU0_RX #20 I2C0_SDA #21 I2C0_SCL #20	PRS_CH3 #12 PRS_CH4 #4 PRS_CH5 #3 PRS_CH6 #15 ACMP0_O #21 ACMP1_O #21
23	PD14	BUSCX BUSDY	TIM0_CC0 #22 TIM0_CC1 #21 TIM0_CC2 #20 TIM0_CDTI0 #19 TIM0_CDTI1 #18 TIM0_CDTI2 #17 TIM1_CC0 #22 TIM1_CC1 #21 TIM1_CC2 #20 TIM1_CC3 #19 LE- TIM0_OUT0 #22 LE- TIM0_OUT1 #21 PCNT0_S0IN #22 PCNT0_S1IN #21	US0_TX #22 US0_RX #21 US0_CLK #20 US0_CS #19 US0_CTS #18 US0_RTS #17 US1_TX #22 US1_RX #21 US1_CLK #20 US1_CS #19 US1_CTS #18 US1_RTS #17 LEU0_TX #22 LEU0_RX #21 I2C0_SDA #22 I2C0_SCL #21	CMU_CLK0 #5 PRS_CH3 #13 PRS_CH4 #5 PRS_CH5 #4 PRS_CH6 #16 ACMP0_O #22 ACMP1_O #22 GPIO_EM4WU4

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
25	VREGVSS	Voltage regulator VSS			
26	VREGSW	DCDC regulator switching node			
27	VREGVDD	Voltage regulator VDD input			
28	DVDD	Digital power supply.			
29	DECOUPLE	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.			
30	IOVDD	Digital IO power supply.			
31	PC10	BUSAX BUSBY	TIM0_CC0 #15 TIM0_CC1 #14 TIM0_CC2 #13 TIM0_CDTI0 #12 TIM0_CDTI1 #11 TIM0_CDTI2 #10 TIM1_CC0 #15 TIM1_CC1 #14 TIM1_CC2 #13 TIM1_CC3 #12 LE- TIM0_OUT0 #15 LE- TIM0_OUT1 #14 PCNT0_S0IN #15 PCNT0_S1IN #14	US0_TX #15 US0_RX #14 US0_CLK #13 US0_CS #12 US0_CTS #11 US0_RTS #10 US1_TX #15 US1_RX #14 US1_CLK #13 US1_CS #12 US1_CTS #11 US1_RTS #10 LEU0_TX #15 LEU0_RX #14 I2C0_SDA #15 I2C0_SCL #14	CMU_CLK1 #3 PRS_CH0 #12 PRS_CH9 #15 PRS_CH10 #4 PRS_CH11 #3 ACMP0_O #15 ACMP1_O #15 GPIO_EM4WU12
32	PC11	BUSAY BUSBX	TIM0_CC0 #16 TIM0_CC1 #15 TIM0_CC2 #14 TIM0_CDTI0 #13 TIM0_CDTI1 #12 TIM0_CDTI2 #11 TIM1_CC0 #16 TIM1_CC1 #15 TIM1_CC2 #14 TIM1_CC3 #13 LE- TIM0_OUT0 #16 LE- TIM0_OUT1 #15 PCNT0_S0IN #16 PCNT0_S1IN #15	US0_TX #16 US0_RX #15 US0_CLK #14 US0_CS #13 US0_CTS #12 US0_RTS #11 US1_TX #16 US1_RX #15 US1_CLK #14 US1_CS #13 US1_CTS #12 US1_RTS #11 LEU0_TX #16 LEU0_RX #15 I2C0_SDA #16 I2C0_SCL #15	CMU_CLK0 #3 PRS_CH0 #13 PRS_CH9 #16 PRS_CH10 #5 PRS_CH11 #4 ACMP0_O #16 ACMP1_O #16 DBG_SWO #3

6.3.1 EFM32PG1 QFN32 with DC-DC GPIO Overview

The GPIO pins are organized as 16-bit ports indicated by letters (A, B, C...), and the individual pins on each port are indicated by a number from 15 down to 0.

Table 6.6. QFN32 with DC-DC GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	PA1	PA0
Port B	PB15	PB14	PB13 (5V)	PB12 (5V)	PB11 (5V)	-	-	-	-	-	-	-	-	-	-	-
Port C	-	-	-	-	PC11 (5V)	PC10 (5V)	-	-	-	-	-	-	-	-	-	-
Port D	PD15 (5V)	PD14 (5V)	PD13 (5V)	PD12 (5V)	PD11 (5V)	PD10 (5V)	PD9 (5V)	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	PF3 (5V)	PF2 (5V)	PF1 (5V)	PF0 (5V)

Note:

- GPIO with 5V tolerance are indicated by (5V).
- The pins PB13, PB12, PB11, PD15, PD14, and PD13 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

Table 6.9. ACMP1 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	Bus
	PB15	PB15						CH31
PB14			PB14					CH30
	PB13	PB13						CH29
PB12			PB12					CH28
	PB11	PB11						CH27
								CH26
								CH25
								CH24
					PF7	PF7		CH23
				PF6			PF6	CH22
					PF5	PF5		CH21
				PF4			PF4	CH20
					PF3	PF3		CH19
				PF2			PF2	CH18
					PF1	PF1		CH17
				PF0			PF0	CH16
								CH15
								CH14
	PA5	PA5						CH13
PA4			PA4					CH12
	PA3	PA3			PC11	PC11		CH11
PA2			PA2	PC10			PC10	CH10
	PA1	PA1			PC9	PC9		CH9
PA0			PA0	PC8			PC8	CH8
	PD15	PD15			PC7	PC7		CH7
PD14			PD14	PC6			PC6	CH6
	PD13	PD13						CH5
PD12			PD12					CH4
	PD11	PD11						CH3
PD10			PD10					CH2
	PD9	PD9						CH1
								CH0

7.2 QFN48 PCB Land Pattern

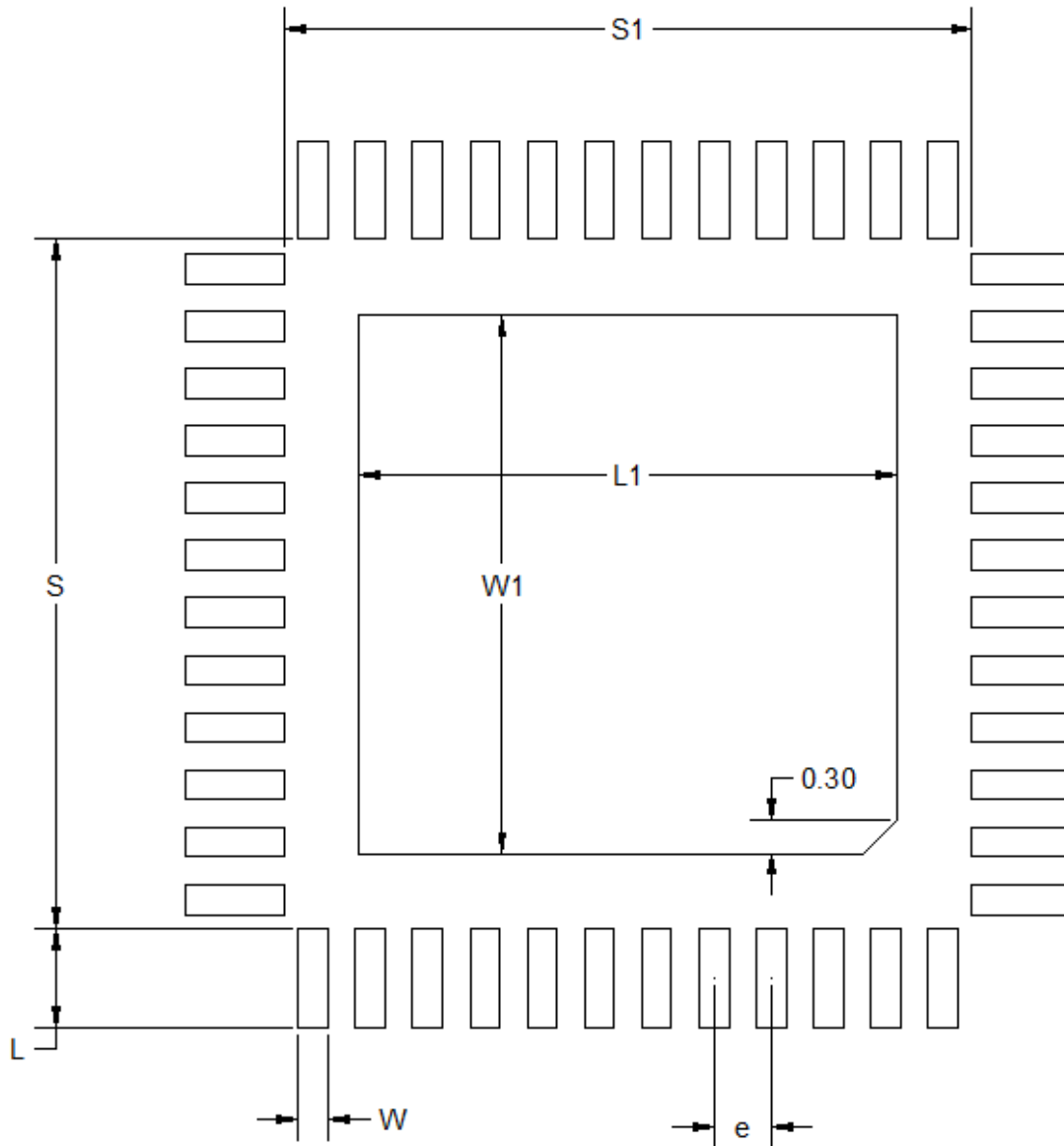


Figure 7.2. QFN48 PCB Land Pattern Drawing

Table 8.1. QFN32 Package Dimensions

Dimension	Min	Typ	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.20 REF		
b	0.18	0.25	0.30
D/E	4.90	5.00	5.10
D2/E2	3.40	3.50	3.60
E	0.50 BSC		
L	0.30	0.40	0.50
K	0.20	—	—
R	0.09	—	0.14
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220, Variation VKKD-4.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

8.2 QFN32 PCB Land Pattern

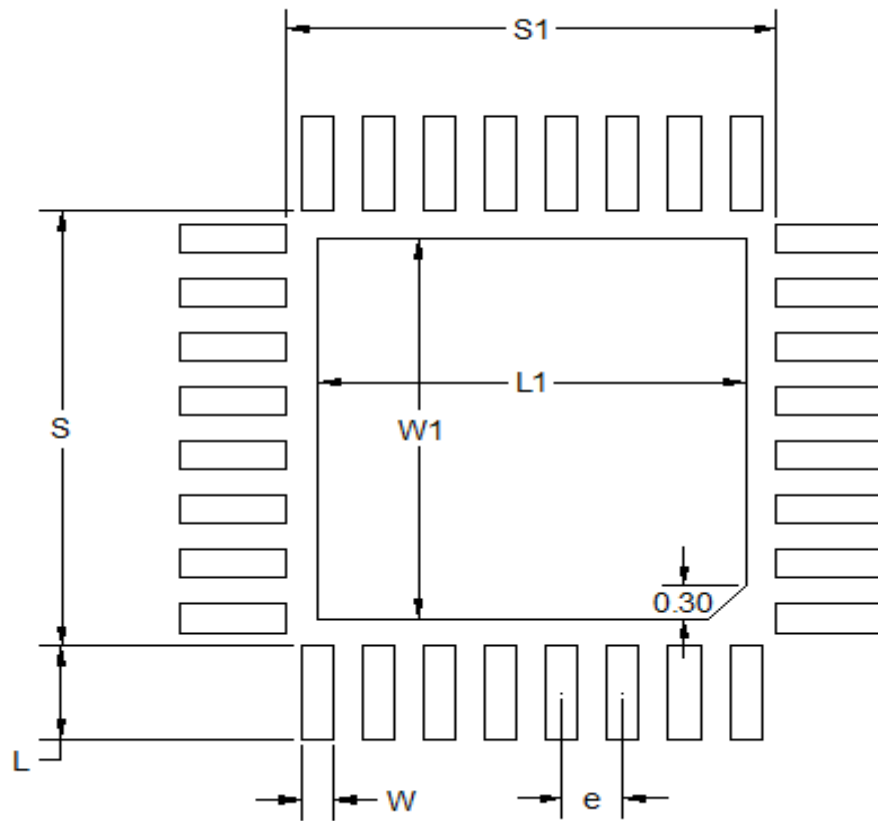


Figure 8.2. QFN32 PCB Land Pattern Drawing

9. Revision History

9.1 Revision 1.1

2016-Oct-26

- System Overview Sections: Minor wording and typographical error fixes.
- Electrical Characteristics: Minor wording and typographical error fixes.
- "HFRCO and AUXHFRCO" table in Electrical Characteristics: f_HFRCO symbol changed to f_HFRCO_ACC.
- Pinout tables: APORT channel details removed from "Analog" column. This information is now found in the APORT client map sections.
- Updated APORT client map sections.

9.2 Revision 1.0

2016-Jul-22

- Electrical Characteristics: Minimum and maximum value statement changed to cover full operating temperature range.
- Finalized Specification Tables. Tables with condition/min/typ/max or footnote changes include:
 - Absolute Maximum Ratings
 - General Operating Conditions
 - DC-DC Converter
 - LFRCO
 - HFRCO and AUXHFRCO
 - ADC
 - IDAC
- Updated Typical Performance Graphs.
- Added note for 5V tolerance to pinout GPIO Overview sections.
- Updated OPN decoder with latest revision.
- Updated Package Marking text with latest descriptions.

9.3 Revision 0.95

2016-04-11

- All OPNs changed to rev C0.
- Electrical specification tables updated with latest characterization data and production test limits.

9.4 Revision 0.31

- Engineering samples note added to ordering information table.

9.5 Revision 0.3

- Re-formatted ordering information table and OPN decoder.
- Removed extraneous sections from dc-dc from system overview.
- Updated table formatting for electrical specifications.
- Updated electrical specifications with latest available data.
- Added I2C and USART SPI timing tables.
- Moved dc-dc graph to typical performance curves.
- Updated APORT tables and APORT references to correct nomenclature.
- Updated top marking description.

9.6 Revision 0.2

Updated ordering table.

Changed "1.62 V to 3.8 V Single Power Supply" to "1.62 V to 3.8 V Power Supply" in the Feature List.